

Omniseal Solutions & Saint-Gobain Businesses Collaborate At Semicon West

Delivering Sealing, Fluid Handling & Grinding Solutions For Critical Semiconductor Processes



Garden Grove, California May 21, 2024 (<u>Issuewire.com</u>) - Omniseal Solutions, a design engineering and manufacturer of precision sealing and wear control solutions for over 60 years, will exhibit at SEMICON WEST in San Francisco from July 9 to 11, at Booth #1133, in collaboration with <u>Saint-Gobain Electronics</u> and <u>Norton Abrasives</u>.

The three businesses join forces to offer a wide range of high-performance solutions that meet the stringent requirements found in the semiconductor fabrication process. With their combined solutions, the businesses support a wide range of critical applications: wafer cleaning and etching equipment, test

sockets, glue dispensers, pumps, valves, fittings, high-purity piping and tubing, back grinding machines, and ultra-thin wafer finishing. The following are solutions most often used in the industry.

- Omniseal® polymers and metals, and Meldin® polyimides
- Furon® pumps, valves, manifolds, fittings, tubing and accessories
- High-precision grinding, slicing, dicing, sawing, thinning, and finishing of electronic components

Branko Rogovic, District Sales Manager – Semiconductor, Omniseal Solutions, said, "Our team is excited to attend this international event again with our Saint-Gobain colleagues to share our sealing and material expertise. Our business is continuously collaborating with key customers to solve their challenges, especially in the current landscape, where high temperature, high pressure, sealing control, wear and friction, and leakage rate are becoming even more stringent. With our proven history of engineering and manufacturing success, our partners are enabled to go beyond in their critical applications."

An emerging trend in the global semiconductor market includes a rising need for resilient sealing solutions that protect sensitive electronic components, withstanding higher temperatures, pressures, and corrosive environments. Omniseal Solutions solves these challenges with their spring-energized seals, metal C-Seals, and thermoset polyimides. These solutions are engineered for sealing and contamination control, which ensure stability and performance in semiconductor applications such as wafer cleaning, etching and chemical mechanical planarization equipment.

Another emerging trend is a focus on environmental protection, driving the demand for more sustainable sealing materials. In rapid response, Omniseal Solutions is creating *PFAS-Free sealing solutions that are minimizing environmental impact. An example in the semiconductor industry is their <u>PFAS-Free*</u> spring-energized seals used in hot melt dispensing machines.

Note: *PFAS-Free here means we do not intentionally add PFAS material in the product, but does not exclude the possibility of traces, as these materials are common in the environment.

Aside from this US-based event, Omniseal Solutions is committed to other semiconductor initiatives, exhibiting at other SEMICON key events.

- <u>SEMICON Taiwan in September</u>: According to <u>The Economist</u>, "Taiwan produces over 60% of the world's semiconductors and over 90% of the most advanced ones."
- SEMICON SEA in May: Malaysia, Singapore, and Vietnam are emerging as new global hubs for semiconductors. Penang, Malaysia, is known as the Silicon Valley of the East and was selected as a semiconductor production base by Intel, AMD, Broadcom, Micron, and Infineon.





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